

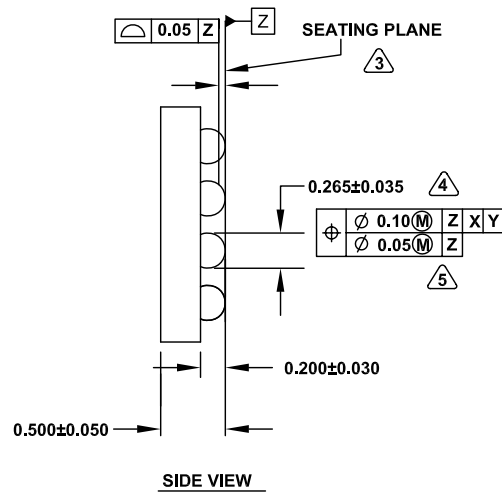
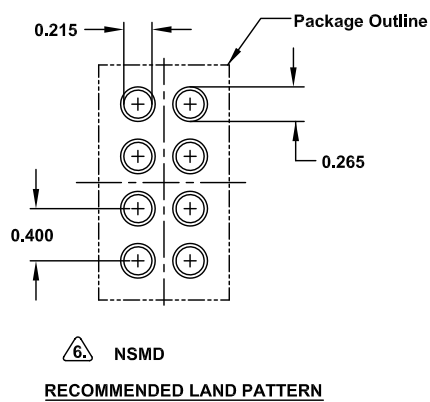
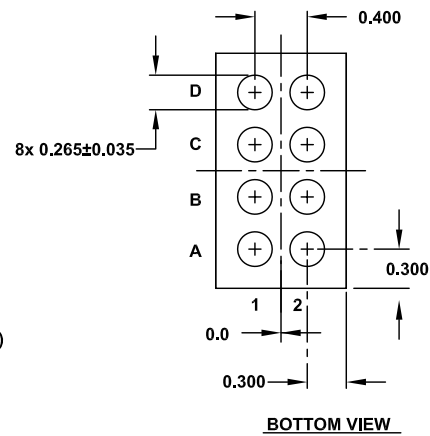
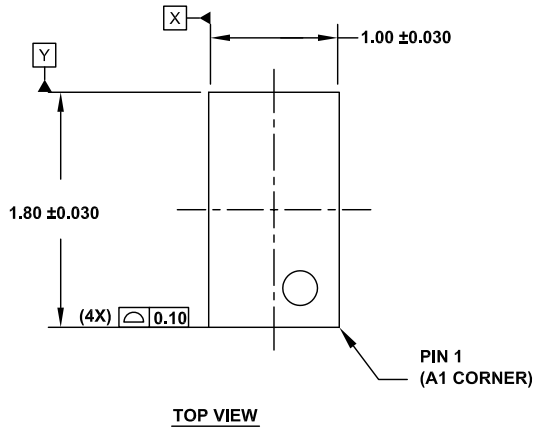
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

W2x4.8

8 Ball Wafer Level Chip Scale Package (WLCSP) 0.4mm Pitch

Rev 0, 6/17



### NOTES:

- All dimensions are in millimeters.
- Dimensions and tolerances per ASMEY 14.5-1994
- Primary datum Z and seating plane are defined by the spherical crowns of the bump.
- Dimension is measured at the maximum bump diameter parallel to primary datum Z.
- Bump position designation per JESD 95-1, SPP-010.
- NSMD refers to non-solder mask defined pad design per Intersil Techbrief. <http://www.intersil.com/data/tb/tb451.pdf>